



# Test Report

**Sample Name:** \_\_\_\_\_ The integrated circuit \_\_\_\_\_

**Sample Type:** \_\_\_\_\_ AT28C64B-15SU-T \_\_\_\_\_

**Manufacturer:** \_\_\_\_\_ Microchip Technology \_\_\_\_\_

**Customer:** \_\_\_\_\_  \_\_\_\_\_

Chuangxin Online Test Center Laboratory

On February 29, 2024

# Test Report

Customer:

Customer Address: N/A

Sample Name: The integrated circuit

Sample Type: AT28C64B-15SU-T

Manufacturer: Microchip Technology

Date Code: 2311+

Package Type: 28-SOIC

Sample Amount: 10 PCS

Check Amount: 10 PCS

Arrived Date: 02/28/2024

Testing Date: 02/28/2024/17: 00 - 02/28/2024/18: 00

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Issued by \_\_\_\_\_  
(Stamp) 

Tested by \_\_\_\_\_

Inspected by \_\_\_\_\_

Approved by \_\_\_\_\_

# Test Item

External visual inspection

Pin correlation test

Programming test

Solderability analysis

Radiography(X-ray)

XRF test

Key functional test(KFT)

Baking

Tape and reel

Top permanency test

Internal visual inspection

SAT test

Cross section

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# Methods & Equipment

## 1.1 Test standard:

- **AS6081A-2023**

## 1.2 Optical microscope:

- Equipment spec:

Optical microscope: SEZ-260 X7-X45(Due date: 7/18/2024)

## 1.3 X-ray flaw detector:

- Equipment spec:

X-ray flaw detector: X6600 70KV/40uA(Due date: 7/18/2024)

## 1.4 Product datasheet:

- 《Microchip Technology AT28C64B-15SU-T》 :

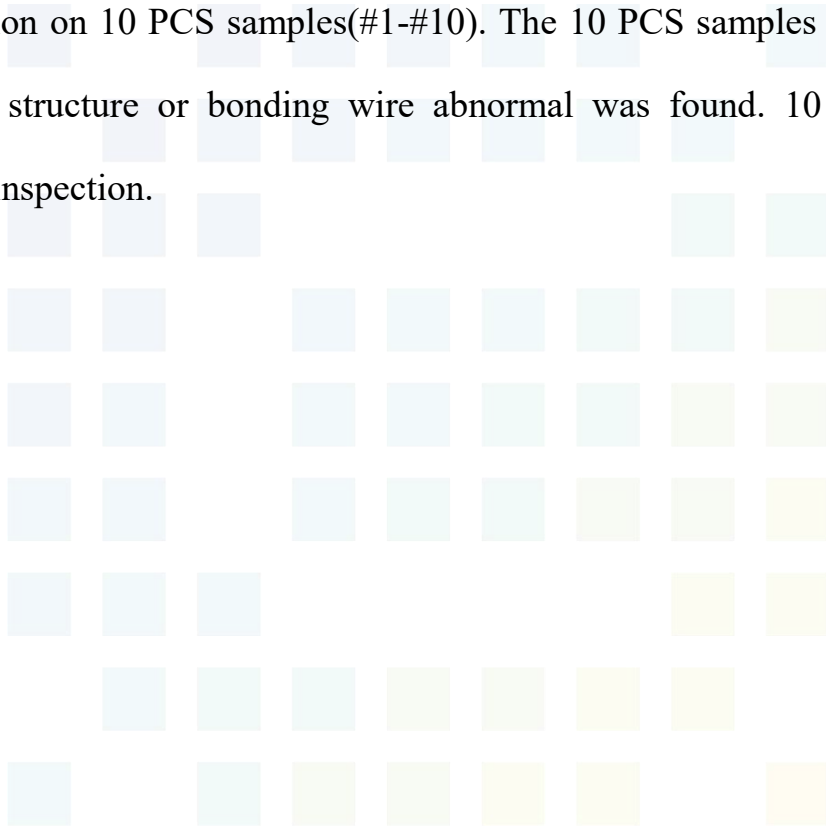
<https://ww1.microchip.com/downloads/en/DeviceDoc/doc0270.pdf>

# Analysis Summary

## Radiography(X-ray):

Applicable standard: **AS6081A-2023**

X-ray inspection on 10 PCS samples(#1-#10). The 10 PCS samples have the same structure. No structure or bonding wire abnormal was found. 10 PCS samples passed X-ray inspection.



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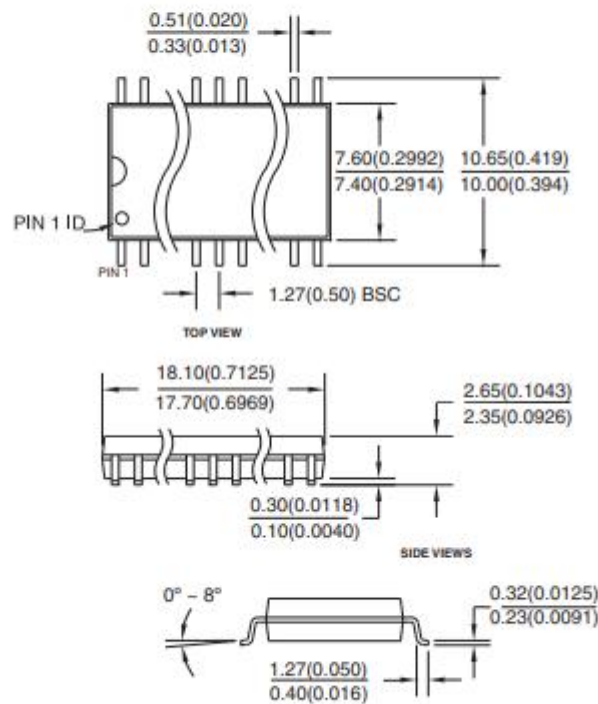


## 1. Device description:

The AT28C64B is a high-performance electrically-erasable and programmable read only memory (EEPROM). Its 64K of memory is organized as 8, 192 words by 8 bits. Manufactured with Atmel's advanced nonvolatile CMOS technology, the device offers access times to 150 ns with power dissipation of just 220 mW. When the device is deselected, the CMOS standby current is less than 100  $\mu$ A.

## 2. Package dimension:

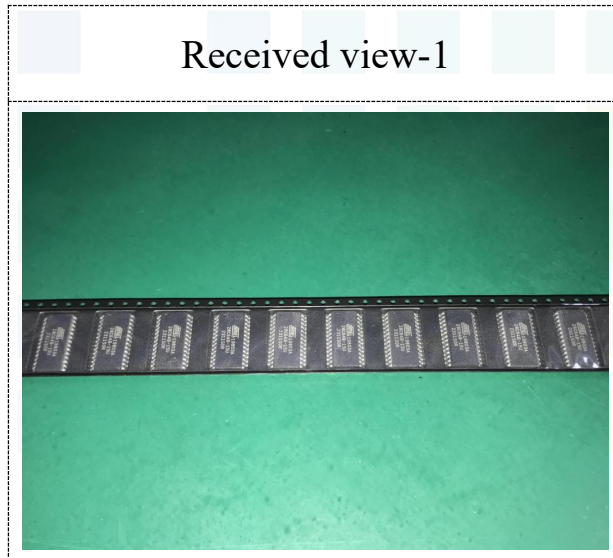
Dimensions in Millimeters and (Inches).  
Controlling dimension: Millimeters.



### 3. Receiving inspection:

<b>Gross Weight</b>	50 g	<b>Parts Total</b>	10 PCS
<b>Number of Boxes</b>	N/A	<b>Full Label</b>	N/A
<b>Package Type</b>	Reel	<b>Moisture Protection</b>	N/A
<b>MSL</b>	N/A	<b>ESD Protection</b>	N/A

Note: All devices contain 10 PCS samples.



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## 4. Radiography(X-ray):

**Applicable standard:AS6081A-2023**

Ambient temperature: 25.3 °C Relative humidity: 55.8 % RH

X-ray inspection on 10 PCS samples. The 10 PCS samples have the same structure.

No structure or bonding wire abnormal was found. 10 PCS samples passed X-ray inspection.

Sample No	Test Items	Result
#1-#10	Whether there are cracks, bonding tilts, or anomalies outside the bonding range in the internal wafer	Pass
	Whether the internal bonding wire is broken, crossed wire, radian exceeding the standard, and solder joint is abnormal	Pass
	Check whether the internal lead rack and substrate structure are abnormal	Pass
	Whether the void at the internal bonding interface is abnormal. Whether the bonding material is separated from the main body, and the accumulation of the bonding material is too high	Pass
	Whether the internal wafer, bonding wire, bonding mode, material, lead frame, substrate structure and internal bonding are consistent when multiple	Pass



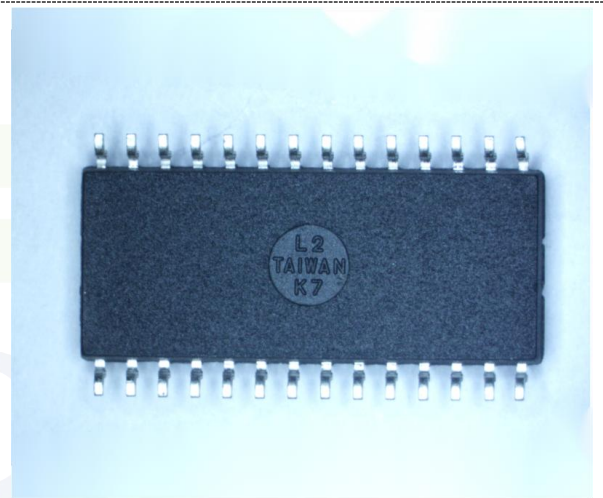


	samples are tested	
	Side view inside the climbing height of the bonding material, the arc of the bonding wire, the distance between the bonding wire and the top, and the first and second solder joints are abnormal	Pass
	Whether there are attached or free particles in the sample exceeding 0.025mm, whether the material is metal	Pass
Note		

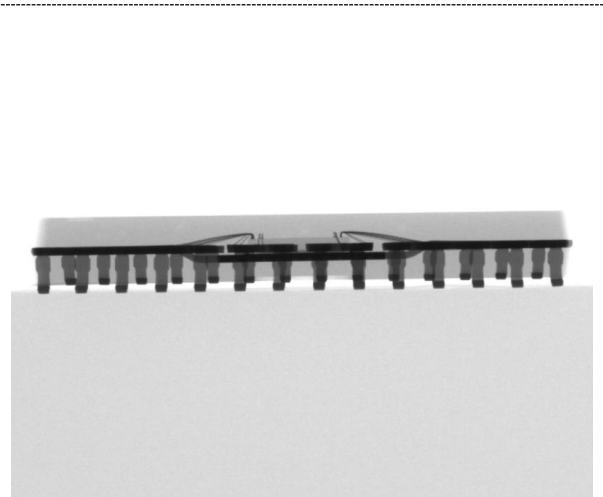
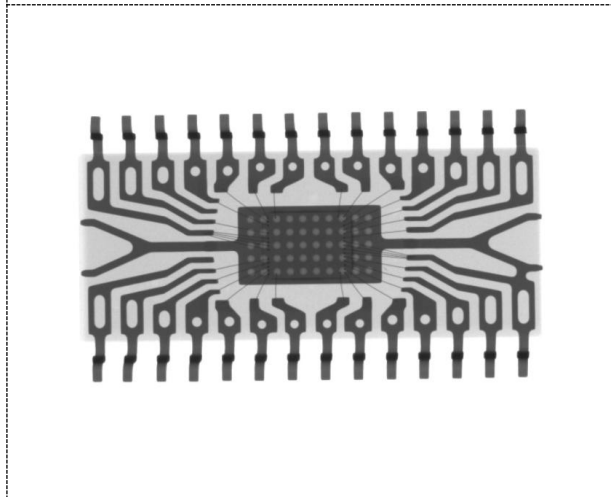
Top	Bottom
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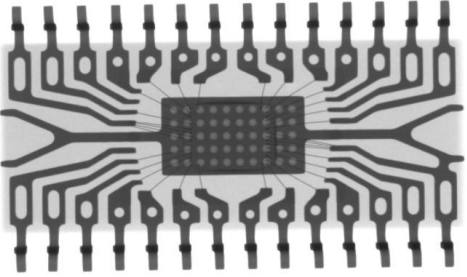
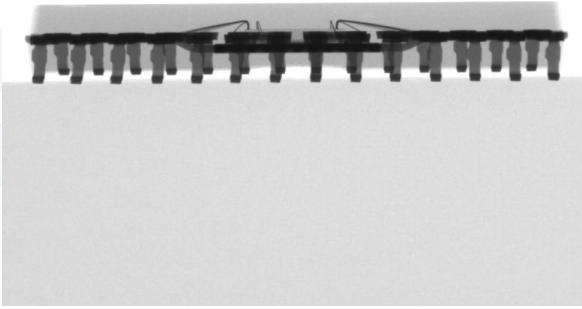
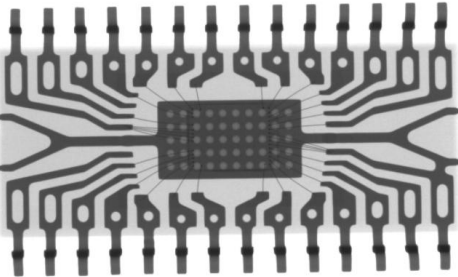
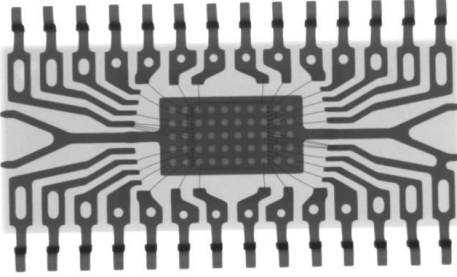
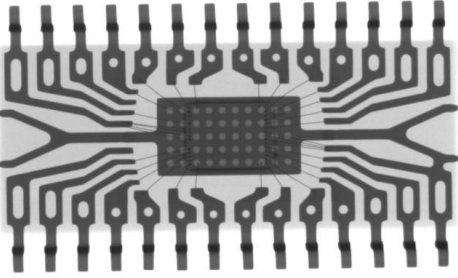
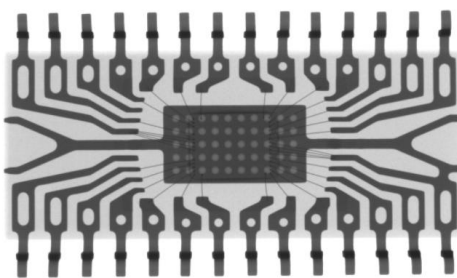
#1-Top view-All



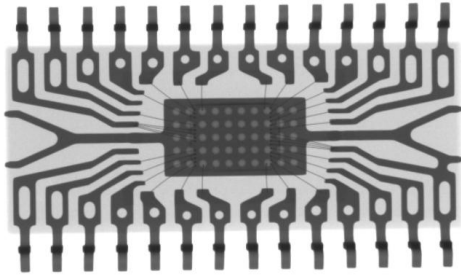
#1-Side view-All



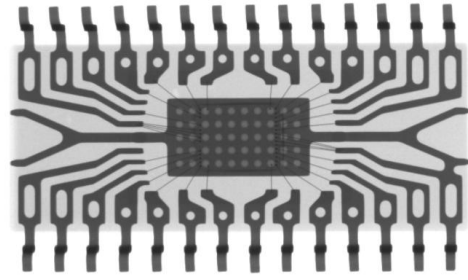
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#2-Top view-All	#2-Side view-All
	
#3-Top view-All	#4-Top view-All
	
#5-Top view-All	#6-Top view-All
	
#7-Top view-All	#8-Top view-All

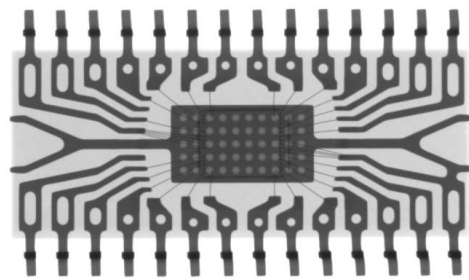
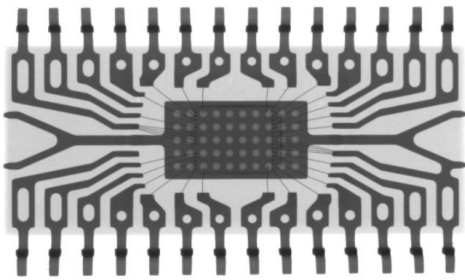
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中



#9-Top view-All



#10-Top view-All



-End of Report-

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## Disclaimer

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2. The copy of the test report is invalid without the stamp of “company seal” and “cross-page seal”.
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5. When there is disagreement with the test report, please submit the issue to us within 15 days from the date of receipt. Overdue information will not be accepted.
6. The test report is only reflective of the test results of testing samples, not of the quality of batch products.
7. The \* indicates subcontract test data.



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